# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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## RB521S30T1G, NSVRB521S30T1G, RB521S30T5G

## **Schottky Barrier Diode**

These Schottky barrier diodes are designed for high-speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

#### Features

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage 0.5 V (max) @  $I_F = 200 \text{ mA}$
- Low Reverse Current
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Reverse Voltage	V <sub>R</sub>	30	Vdc	
Forward Current DC	١ <sub>F</sub>	200	mA	
Peak Forward Surge Current (Note 1)      I <sub>FSM</sub> 1.0      A				
ESD Bating: Class 1C per Human Body Model				

Class C per Machine Model

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. 60 Hz for 1 cycle.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 2) $T_A = 25^{\circ}C$ Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +125	°C

2. FR-5 Minimum Pad.



#### **ON Semiconductor®**

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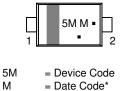
#### **30 V SCHOTTKY BARRIER DIODE**



SOD-523 CASE 502

1 0 2 CATHODE ANODE

#### MARKING DIAGRAM



= Pb-Free Package

(Note: Microdot may be in either location) \*Date Code orientation may vary depending up-

on manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
RB521S30T1G	SOD-523 (Pb-Free)	4 mm Pitch 3,000/Tape & Reel
NSVRB521S30T1G	SOD-523 (Pb-Free)	4 mm Pitch 3,000/Tape & Reel
RB521S30T5G	SOD-523 (Pb-Free)	2 mm Pitch 8,000/Tape & Reel

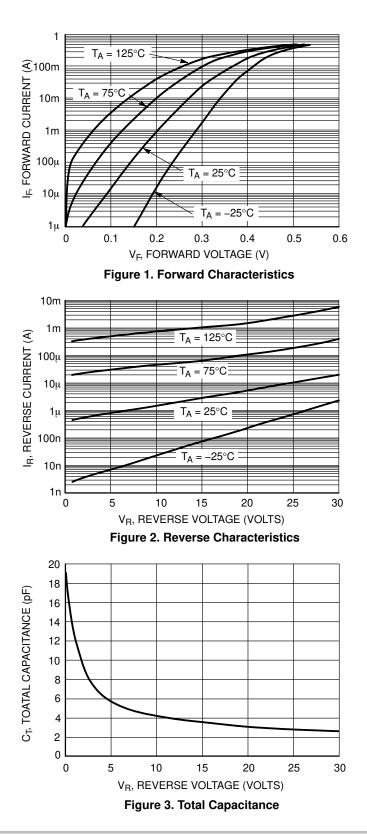
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### RB521S30T1G, NSVRB521S30T1G, RB521S30T5G

#### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

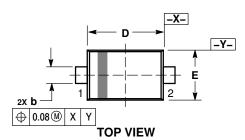
Characteristic	Symbol	Min	Тур	Мах	Unit
Reverse Leakage (V <sub>R</sub> = 10 V)	I <sub>R</sub>	-	-	30.0	μA
Forward Voltage (I <sub>F</sub> = 200 mA)	V <sub>F</sub>	-	-	0.50	Vdc

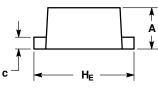


#### RB521S30T1G, NSVRB521S30T1G, RB521S30T5G

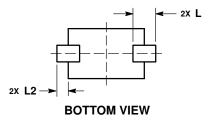
#### PACKAGE DIMENSIONS

SOD-523 CASE 502 ISSUE E







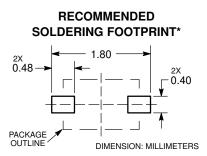


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS OF AND E DO NOT INCLUDE MOLD FLASH, PRO-TRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.50	0.60	0.70	
b	0.25	0.30	0.35	
с	0.07	0.14	0.20	
D	1.10	1.20	1.30	
E	0.70	0.80	0.90	
ΗE	1.50	1.60	1.70	
L	0.30 REF			
L2	0.15	0.20	0.25	

STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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